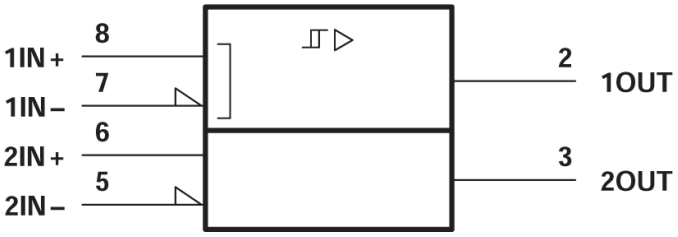
uA9637A 双路差分线路接收器

1 特性

- 符合或超出 ANSI 标准 EIA/TIA-422-B 和 EIA/TIA-423-B 以及 ITU 建议 V.10 和 V.11 的要求
- 单一 5V 电源供电下工作
- 宽共模电压范围
- 高输入阻抗
- 兼容 TTI 的输出
- 高速肖特基电路
- 8 引脚双列直插式和小外形封装
- 旨在可与 National DS9637A 互换

2 应用

- 工厂自动化
- 交流和伺服电机驱动器



逻辑符号†

3 说明

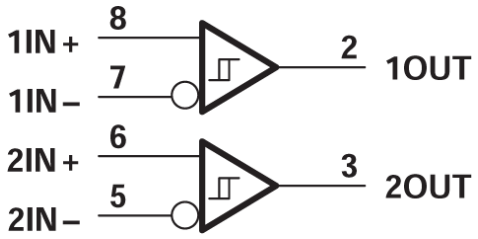
uA9637A 是一款双路差分线路接收器，符合 ANSI 标准 EIA/TIA-422-B 和 EIA/TIA-423-B 以及 ITU 建议 V.10 和 V.11 规范的要求。线路接收器采用肖特基电路，并具有 TTL 兼容输出。输入与单端或差分线路系统兼容。该器件由单一 5V 电源供电，采用 8 引脚双列直插式封装或小外形封装。

uA9637A 的额定工作温度范围为 0°C 至 70°C。

封装信息

器件型号	封装(1)	封装尺寸(2)
uA9637A	SOIC（D，8）	4.9mm × 6mm
	PDIP（P，8）	9.81mm × 9.43mm

(1) 有关更多信息，请参阅 节 11。
(2) 封装尺寸（长 × 宽）为标称值，并包括引脚（如适用）。



逻辑图

† 此符号符合 ANSI/IEEE 标准 91-1984 和 IEC 出版物 617-12。

Table of Contents

4 Pin Configuration and Functions

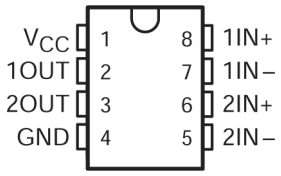


图 4-1. D (SOIC) or P (PDIP) Package (Top View)

表 4-1. Pin Functions

PIN		TYPE[1]	DESCRIPTION
NAME	NO.		
V_{CC}	1	POW	5V (+/-5%) Positive Supply Connection Pin
1OUT	2	O	Single Ended Output for Channel 1 Differential Receiver
2OUT	3	O	Single Ended Output for Channel 2 Differential Receiver
GND	4	GND	Device Ground
2IN-	5	I	Inverting Differential Input for Channel 2's Differential Receiver
2IN+	6	I	Non-Inverting Differential Input for Channel 2's Differential Receiver
1IN-	7	I	Inverting Differential Input for Channel 1's Differential Receiver
1IN+	8	I	Non-Inverting Differential Input for Channel 1's Differential Receiver

(1) Signal Types: I = Input, O = Output, I/O = Input or Output, POW = Power, GND = Ground.

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range (see Note 1)	–0.5	7	V
V_I	Input voltage		±15	V
V_{ID}	Differential input voltage (see (3))		±15	V
V_O	Output voltage range (see (2))	–0.5	5.5	V
I_{OL}	Low-level output current		50	mA
	Continuous total dissipation	See Dissipation Rating Table		
T_A	Operating free-air temperature range	0	70	°C
T_{stg}	Storage temperature range	–65	150	°C
	Lead temperature 1,6mm (1/16 inch) from case for 10 seconds		260	°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential input voltage, are with respect to the network ground terminal.
(3) Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.

5.2 Dissipation Rating Table

PACKAGE	$T_A \leq 25°C$ POWER RATING	OPERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING
D	725mW	5.8mW/°C	464mW
P	1000mW	8.0mW/°C	640mW

5.3 Recommended Operating Conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.75	5	5.25	V
Common-mode input voltage, V_{IC}			±7	V
Operating free-air temperature, T_A	0		70	°C

5.4 Thermal Resistance Characteristics

THERMAL METRIC(1)		D (SOIC)	P (PDIP)	UNIT
		8 Pins	8 Pins	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	116.7	65.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	56.3	54.7	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	63.4	42.1	°C/W
ψ_{JT}	Junction-to-top characterization parameter	8.8	23	°C/W
ψ_{JB}	Junction-to-board characterization parameter	62.6	41.7	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC package thermal metrics* application report.

5.5 Electrical Characteristics

over recommended ranges of supply voltage, common-mode input voltage, and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	See (4)				0.2	V
						0.4	
V_{IT-}	Negative-going input threshold voltage	See (4)		-0.2			V
				-0.4(2)			
V_{hys}	Hysteresis voltage (V_{IT+}-V_{IT-})				70		mV
V_{OH}	High-level output voltage	V_{ID} = 0.2V,	I_O = -1mA	2.5	1.5		V
V_{OL}	Low-level output voltage	V_{ID} = -0.2V,	I_O = 20mA		0.35	0.5	V
I_I	Input current	V_{CC} = 0 to 5.5V,	V_I = 10V		1.1	1.25	mA
		See (5)	V_I = -10V		-1.6	-1.25	
I_{OS}	Short-circuit output current(3)	V_O = 0,	V_{ID} = 0.2V	-40	-75	-100	mA
I_{CC}	Supply current	V_{ID} = -0.5V,	No load		35	50	mA

(1) All typical values are at V_{CC} = 5 V, T_A = 25°C.
(2) The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold levels only.
(3) Only one output should be shorted at a time, and duration of the short circuit should not exceed one second.
(4) The expanded threshold parameter is tested with a 500-Ω resistor in series with each input.
(5) The input not under test is grounded.

5.6 Switching Characteristics

V_{CC} = 5V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	C_L = 30pF, See 图 6-1		15	25	ns
t_{PHL}	Propagation delay time, high- to low-level output			13	25	ns

5.7 Typical Characteristics

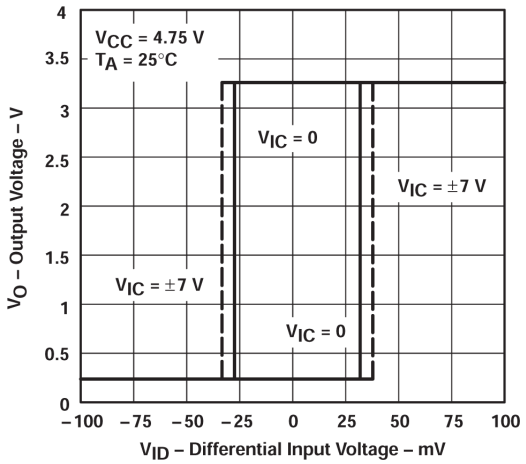


图 5-1. Output Voltage vs Differential Input Voltage

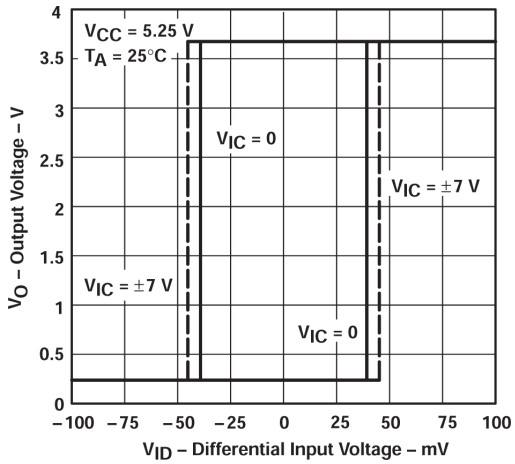


图 5-2. Output Voltage vs Differential Input Voltage

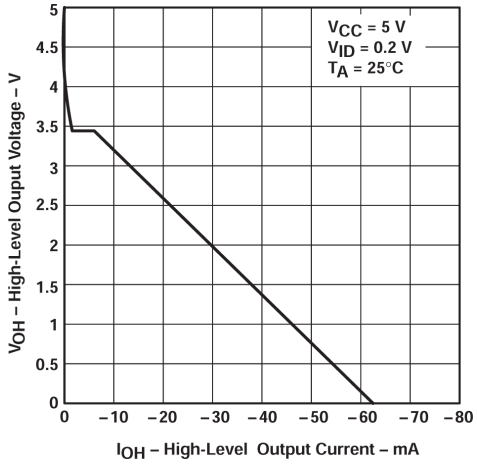


图 5-3. High-level Output Voltage vs High-level Output Current

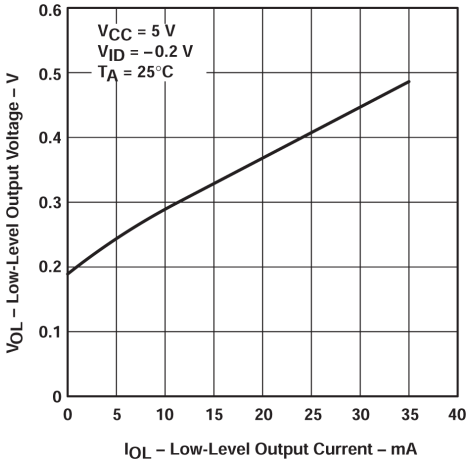


图 5-4. Low-level Output Voltage vs Low-level Output Current

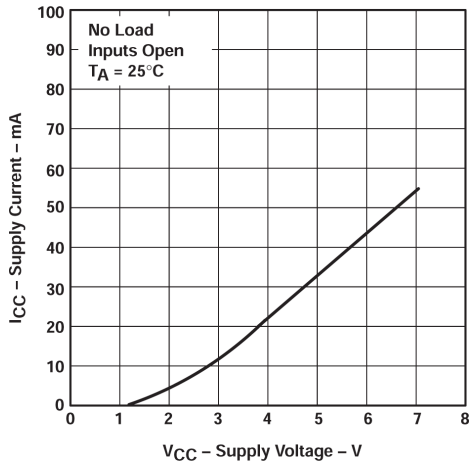
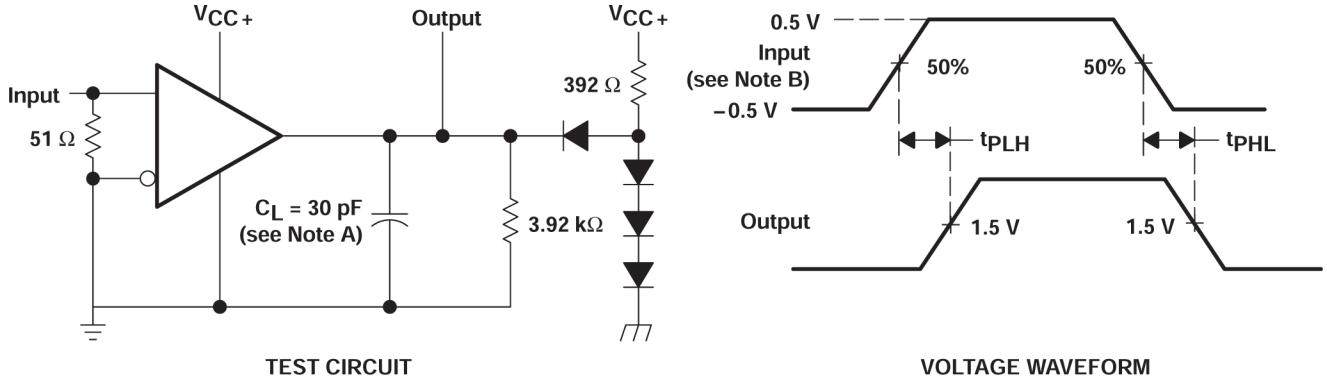


图 5-5. Supply Current vs Supply Voltage

6 Parameter Measurement Information



TEST CIRCUIT VOLTAGE WAVEFORM

A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: $t_r \leqslant 5$ ns, $t_f \leqslant 5$ ns, PRR $\leqslant 5$ MHz, duty cycle = 50%.

图 6-1. Test Circuit and Voltage Waveform

7 Detailed Description

7.1 Device Functional Modes

表 7-1. Functional Table (Each Receiver)

DIFFERENTIAL INPUTS A – B (V_{ID})	ENABLES[1]		OUTPUT Y
	G	$\overline{G}$	
$V_{ID} \leqslant -0.2$ V	H	X	L
	X	L	
-0.2 V < V_{ID} < -0.01 V	H	X	?
	X	L	
-0.01 V $\leqslant V_{ID}$	H	X	H
	X	L	
X	L	H	Z
	OPEN	OPEN	
Short circuit	H	X	H
	X	L	
Open circuit	H	X	H

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off), ? = indeterminate

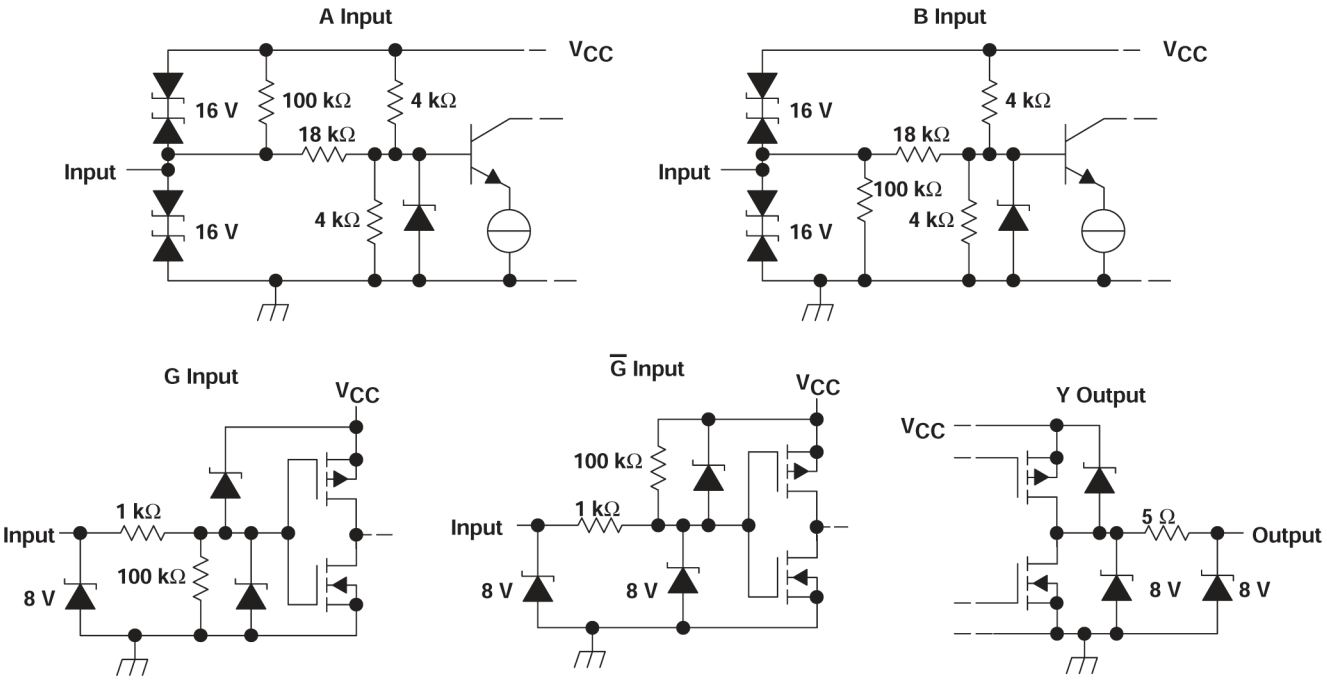
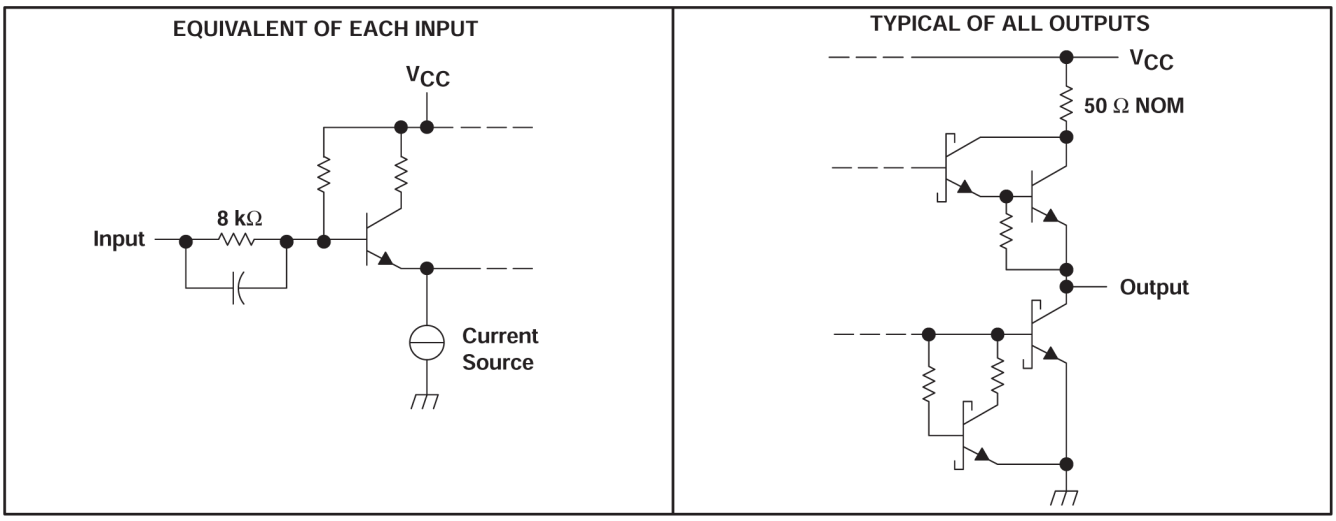


图 7-1. Equivalent Input and Output Schematic Diagrams

7.1.1 Schematics of Inputs and Outputs



8 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客 户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

8.1 Typical Application

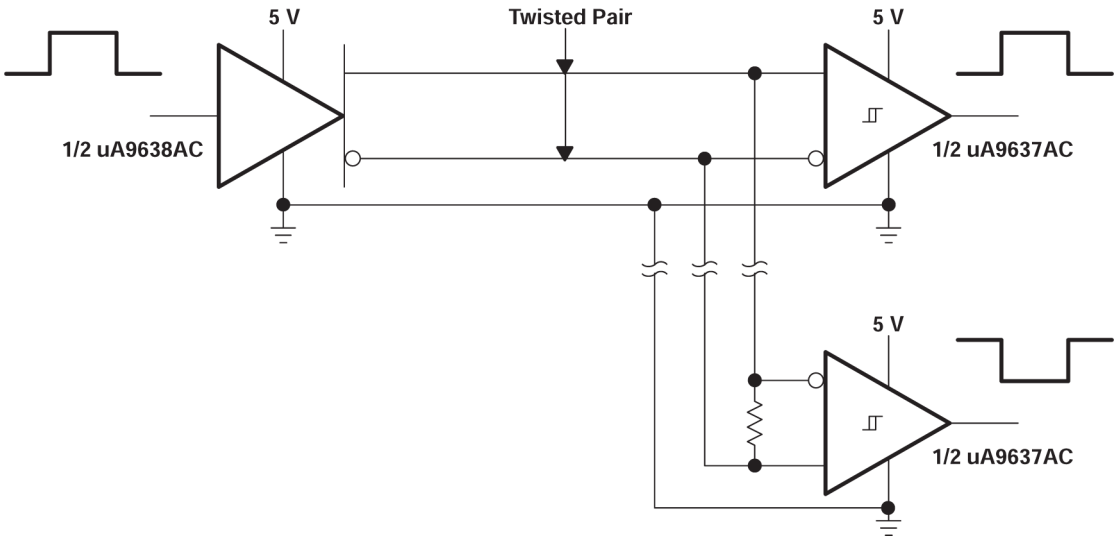


图 8-1. EIA/TIA-422-B System Applications

9 Device and Documentation Support

9.1 支持资源

TI E2E™ 中文支持论坛是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的使用条款。

9.2 商标

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

9.3 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

9.4 术语表

TI 术语表	本术语表列出并解释了术语、首字母缩略词和定义。

10 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision B (May 1995) to Revision C (January 2024)	Page
• 更改了整个文档中的表格、图和交叉参考的编号格式	1

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UA9637ACD	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	0 to 70	9637AC	
UA9637ACDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	9637AC	Samples
UA9637ACDRE4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	9637AC	Samples
UA9637ACDRG4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	9637AC	Samples
UA9637ACP	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	UA9637ACP	Samples
UA9637ACPS	ACTIVE	SO	PS	8	80	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		UA9637A	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

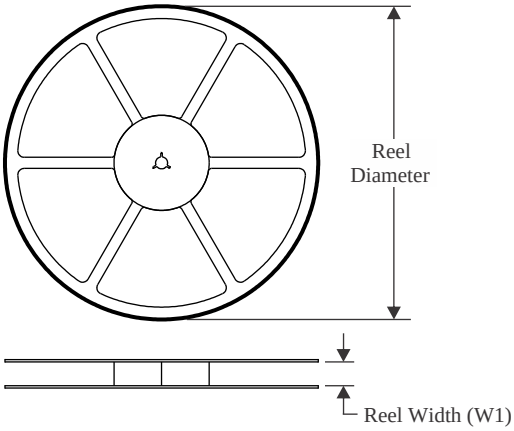
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

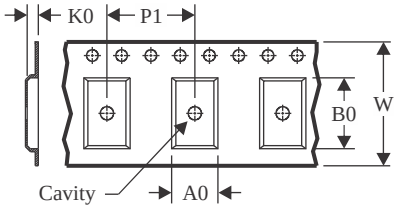
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

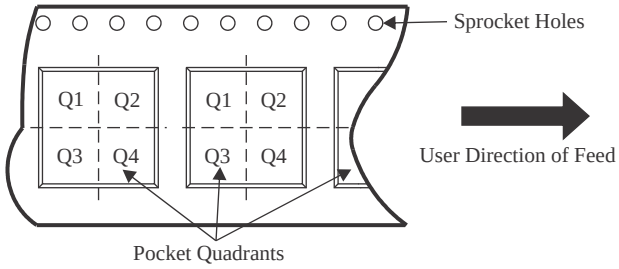


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

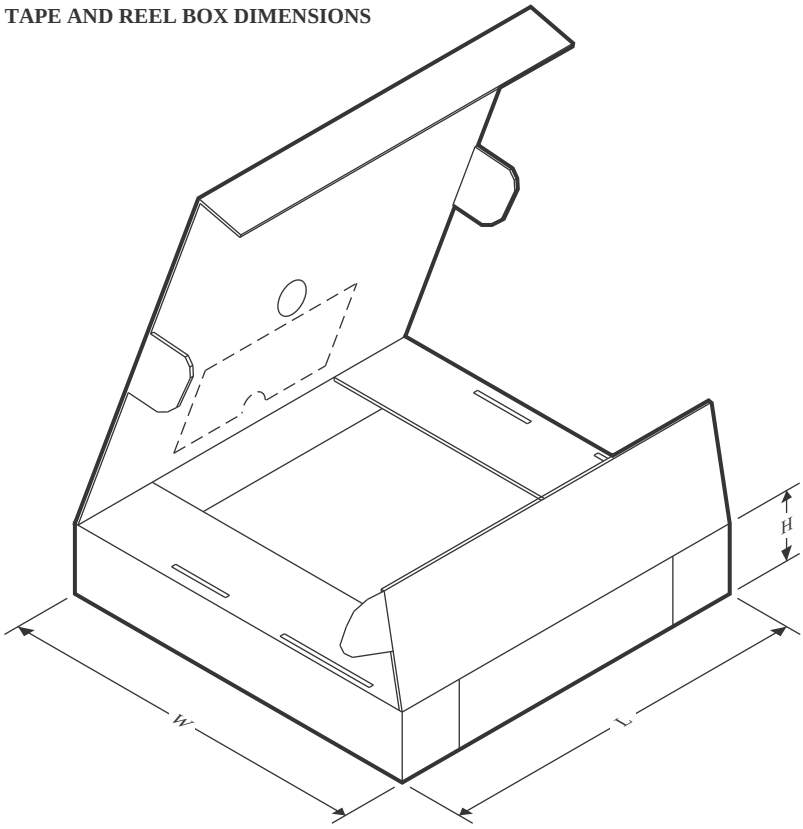
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA9637ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

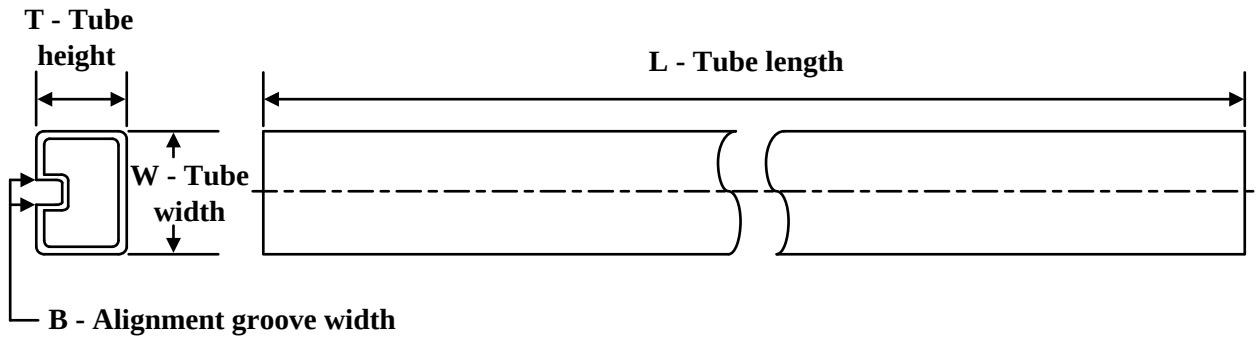
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

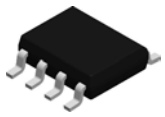
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA9637ACDR	SOIC	D	8	2500	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
UA9637ACD	D	SOIC	8	75	507	8	3940	4.32
UA9637ACP	P	PDIP	8	50	506	13.97	11230	4.32
UA9637ACPS	PS	SOP	8	80	530	10.5	4000	4.1

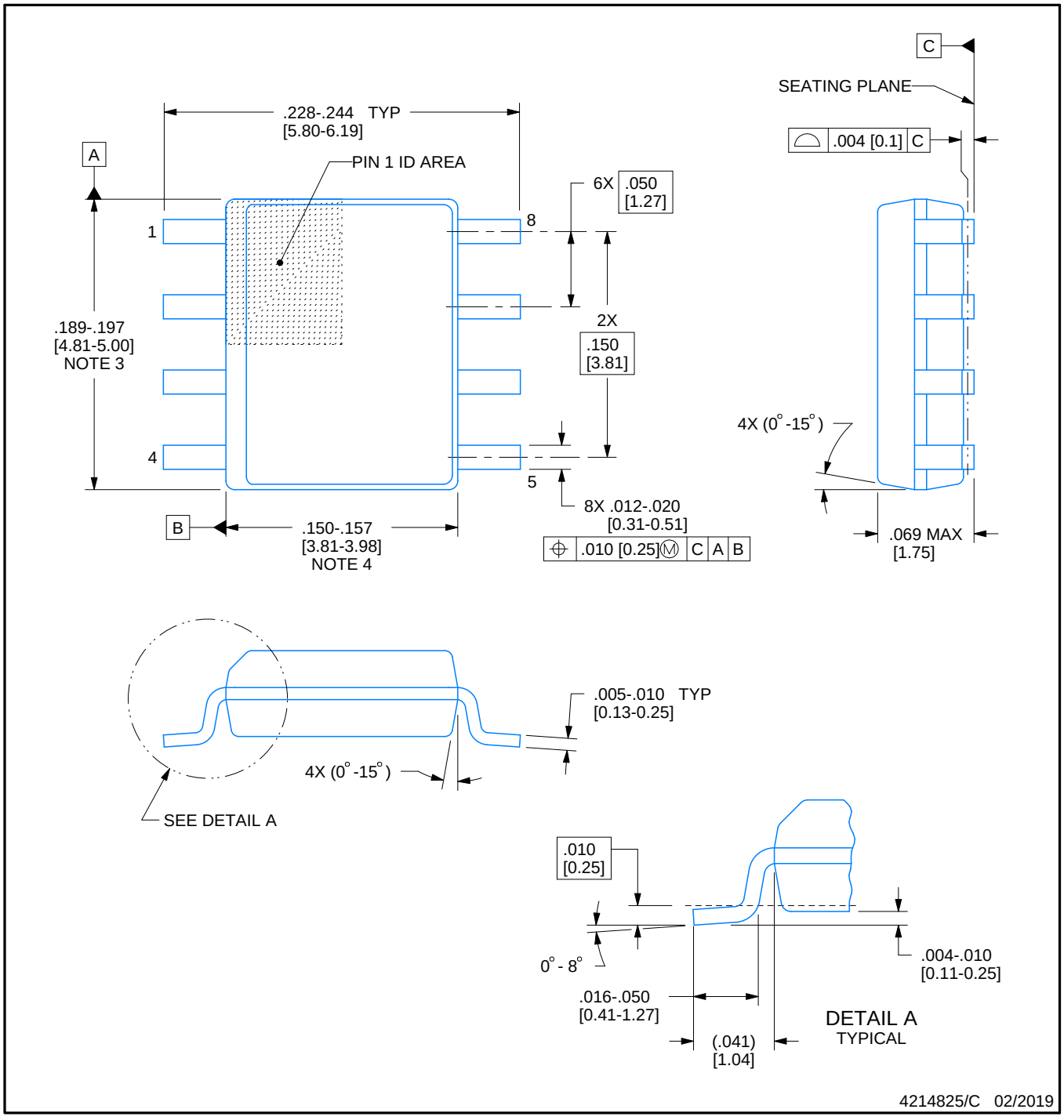


PACKAGE OUTLINE

D0008A

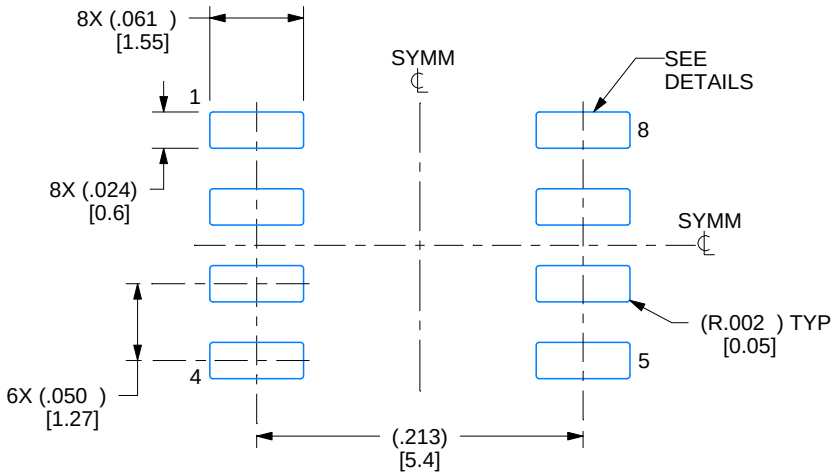
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

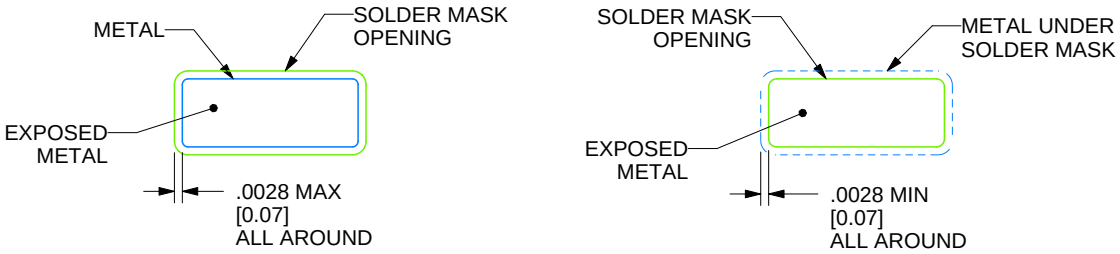


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

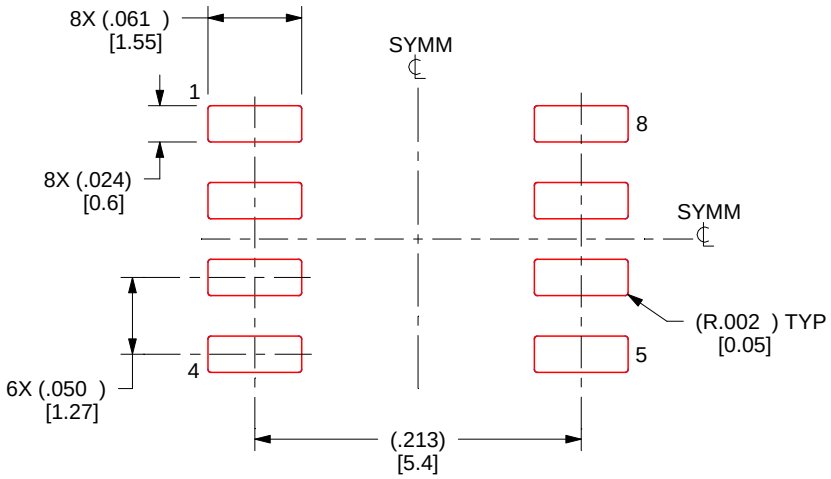
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

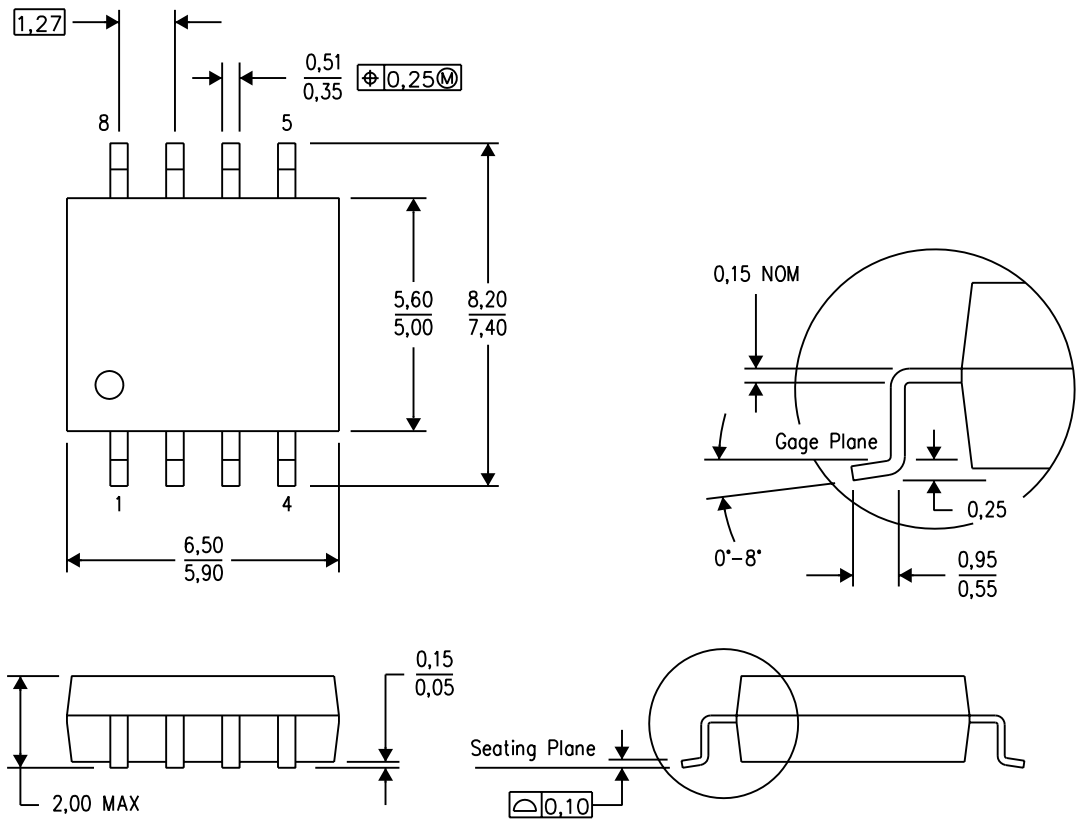
4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

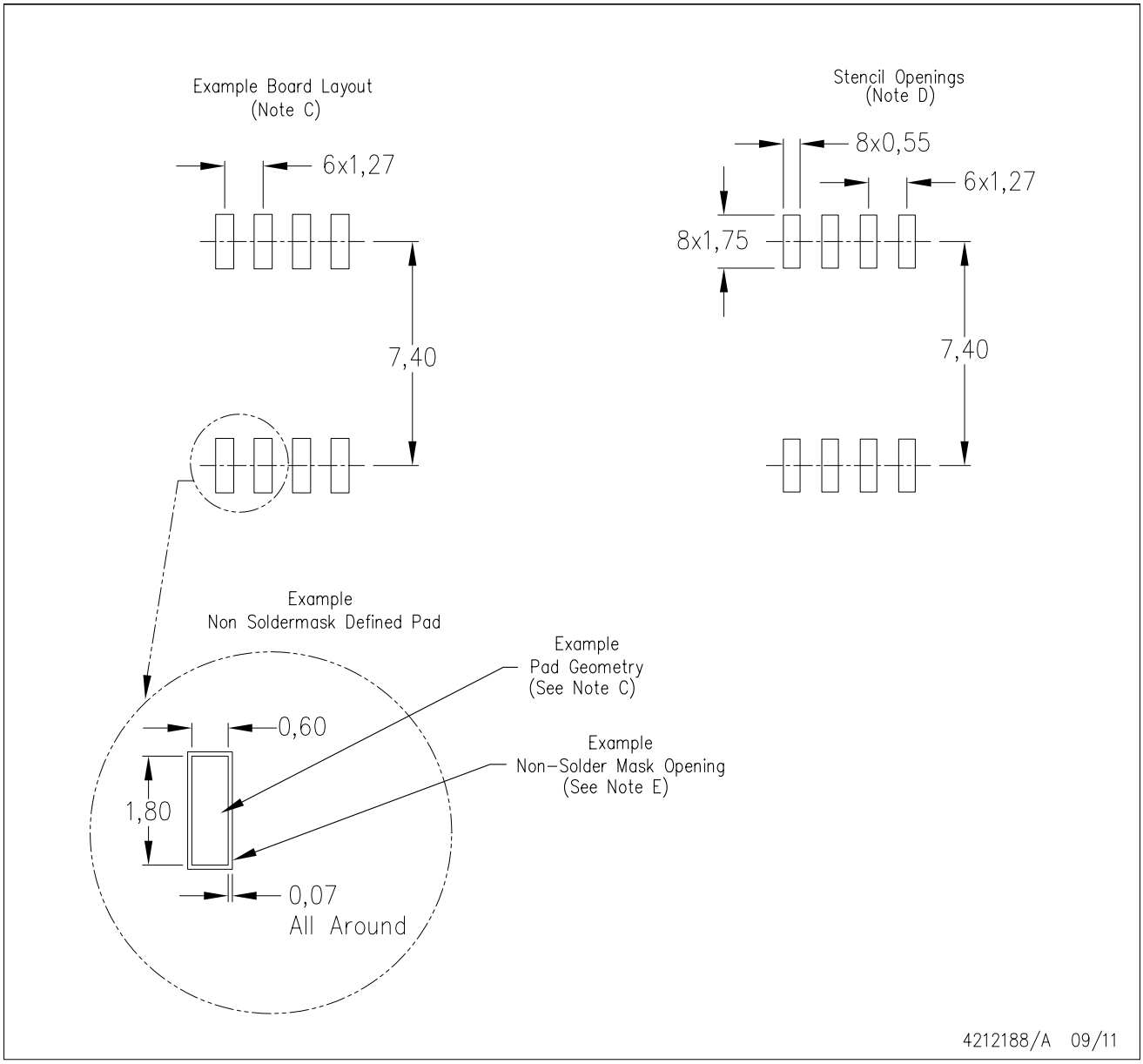
PS (R-PDSO-G8) **PLASTIC SMALL-OUTLINE PACKAGE**



4040063/C 03/03

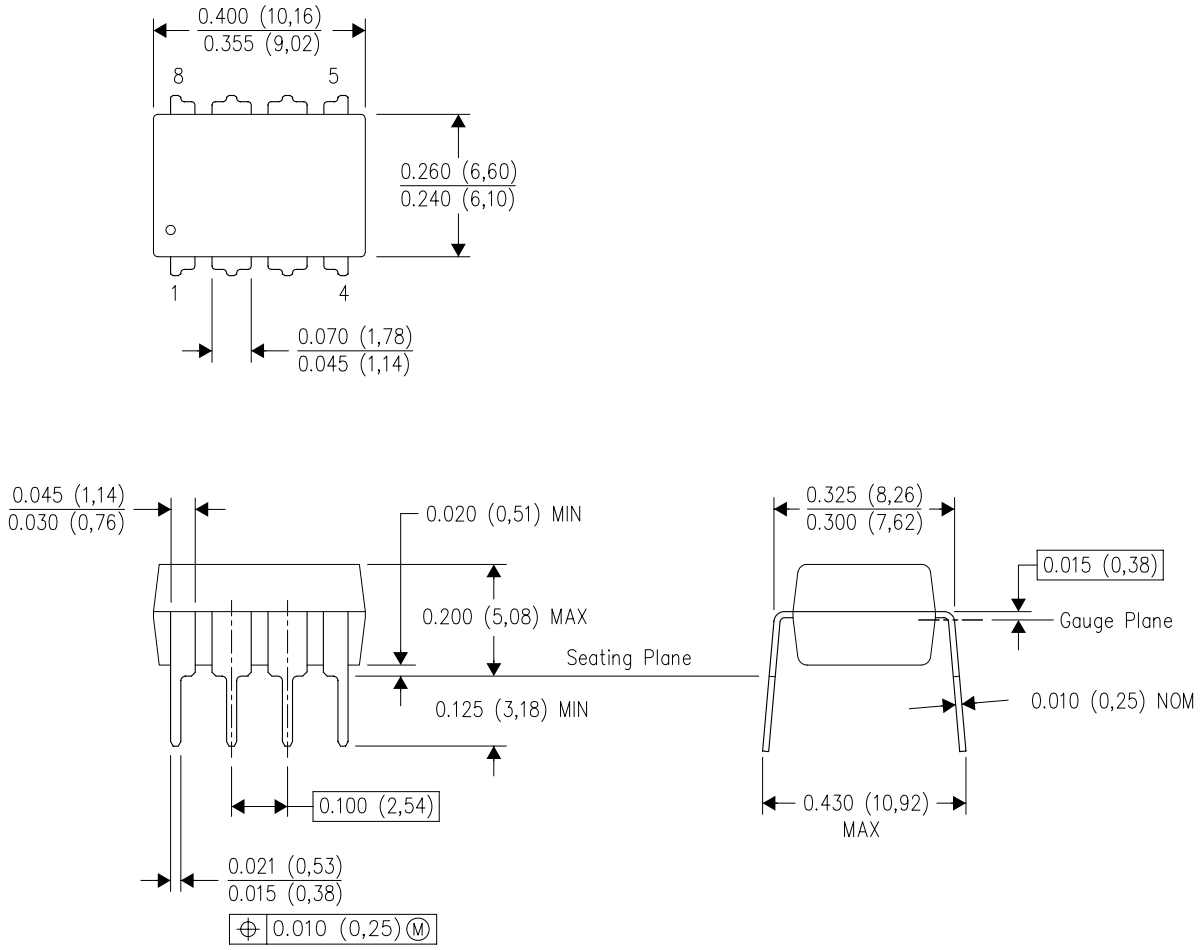
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

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